

**EH1145HSTS-4.9152M**
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**REGULATORY COMPLIANCE** (Data Sheet downloaded on Oct 30, 2016)

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**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 8 Pin DIP Metal Thru-Hole 4.9152MHz ±50ppm 0°C to +70°C

**ELECTRICAL SPECIFICATIONS**

|                                       |                                                                                                                                                                                                                                   |
|---------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency                     | 4.9152MHz                                                                                                                                                                                                                         |
| Frequency Tolerance/Stability         | ±50ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration.) |
| Aging at 25°C                         | ±5ppm/year Maximum                                                                                                                                                                                                                |
| Operating Temperature Range           | 0°C to +70°C                                                                                                                                                                                                                      |
| Supply Voltage                        | 5.0Vdc ±10%                                                                                                                                                                                                                       |
| Input Current                         | 50mA Maximum (No Load)                                                                                                                                                                                                            |
| Output Voltage Logic High (Voh)       | 2.4Vdc Minimum with TTL Load, Vdd-0.4Vdc Minimum with HCMOS Load (IOH = -16mA)                                                                                                                                                    |
| Output Voltage Logic Low (Vol)        | 0.4Vdc Maximum with TTL Load, 0.5Vdc Maximum with HCMOS Load (IOL = +16mA)                                                                                                                                                        |
| Rise/Fall Time                        | 6nSec Maximum (Measured at 0.8Vdc to 2.0Vdc with TTL Load; Measured at 20% to 80% of waveform with HCMOS Load)                                                                                                                    |
| Duty Cycle                            | 50 ±10(%) (Measured at 1.4Vdc with TTL Load or at 50% of waveform with HCMOS Load)                                                                                                                                                |
| Load Drive Capability                 | 10TTL Load or 50pF HCMOS Load Maximum                                                                                                                                                                                             |
| Output Logic Type                     | CMOS                                                                                                                                                                                                                              |
| Pin 1 Connection                      | Tri-State (Disabled Output: High Impedance)                                                                                                                                                                                       |
| Tri-State Input Voltage (Vih and Vil) | +2.2Vdc Minimum to enable output, +0.8Vdc Maximum to disable output (High Impedance), No Connect to enable output.                                                                                                                |
| Absolute Clock Jitter                 | ±250pSec Maximum, ±100pSec Typical                                                                                                                                                                                                |
| One Sigma Clock Period Jitter         | ±50pSec Maximum, ±30pSec Typical                                                                                                                                                                                                  |
| Start Up Time                         | 10mSec Maximum                                                                                                                                                                                                                    |
| Storage Temperature Range             | -55°C to +125°C                                                                                                                                                                                                                   |

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

|                              |                                       |
|------------------------------|---------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity               | MIL-STD-883, Method 2004              |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210               |
| Resistance to Solvents       | MIL-STD-202, Method 215               |
| Solderability                | MIL-STD-883, Method 2003              |
| Temperature Cycling          | MIL-STD-883, Method 1010              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION     |
|-----|----------------|
| 1   | Tri-State      |
| 4   | Case/Ground    |
| 5   | Output         |
| 8   | Supply Voltage |

| LINE | MARKING                                                                                        |
|------|------------------------------------------------------------------------------------------------|
| 1    | ECLIPTEK                                                                                       |
| 2    | EH11TS<br>EH11=Product Series                                                                  |
| 3    | 4.9152M                                                                                        |
| 4    | XXYYZZ<br>XX=Ecliptek Manufacturing<br>Code<br>Y=Last Digit of the Year<br>ZZ=Week of the Year |

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OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for TTL Output

| Output Load<br>Drive Capability | R <sub>L</sub> Value<br>(Ohms) | C <sub>L</sub> Value<br>(pF) |
|---------------------------------|--------------------------------|------------------------------|
| 10TTL                           | 390                            | 15                           |
| 5TTL                            | 780                            | 15                           |
| 2TTL                            | 1100                           | 6                            |
| 10LSTTL                         | 2000                           | 15                           |
| 1TTL                            | 2200                           | 3                            |

Table 1: R<sub>L</sub> Resistance Value and C<sub>L</sub> Capacitance Value Vs. Output Load Drive Capability



- Note 1: An external 0.1µF low frequency tantalum bypass capacitor in parallel with a 0.01µF high frequency ceramic bypass capacitor close to the package ground and V<sub>DD</sub> pin is required.
- Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.
- Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance.
- Note 4: Resistance value R<sub>L</sub> is shown in Table 1. See applicable specification sheet for 'Load Drive Capability'.
- Note 5: All diodes are MMBD7000, MMBD914, or equivalent.

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**Test Circuit for CMOS Output**

Note 1: An external 0.1 $\mu$ F low frequency tantalum bypass capacitor in parallel with a 0.01 $\mu$ F high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

|                                     |                                      |
|-------------------------------------|--------------------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 3°C/Second Maximum                   |
| Preheat                             |                                      |
| - Temperature Minimum (Ts MIN)      | 150°C                                |
| - Temperature Typical (Ts TYP)      | 175°C                                |
| - Temperature Maximum (Ts MAX)      | 200°C                                |
| - Time (ts MIN)                     | 60 - 180 Seconds                     |
| Ramp-up Rate (Tl to Tp)             | 3°C/Second Maximum                   |
| Time Maintained Above:              |                                      |
| - Temperature (Tl)                  | 217°C                                |
| - Time (tL)                         | 60 - 150 Seconds                     |
| Peak Temperature (Tp)               | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (Tp Target) | 250°C +0/-5°C                        |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds                      |
| Ramp-down Rate                      | 6°C/Second Maximum                   |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                    |
| Moisture Sensitivity Level          | Level 1                              |

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 185°C

|                                     |                            |
|-------------------------------------|----------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 5°C/Second Maximum         |
| Preheat                             |                            |
| - Temperature Minimum (Ts MIN)      | N/A                        |
| - Temperature Typical (Ts TYP)      | 150°C                      |
| - Temperature Maximum (Ts MAX)      | N/A                        |
| - Time (ts MIN)                     | 60 - 120 Seconds           |
| Ramp-up Rate (Tl to Tp)             | 5°C/Second Maximum         |
| Time Maintained Above:              |                            |
| - Temperature (Tl)                  | 150°C                      |
| - Time (tL)                         | 200 Seconds Maximum        |
| Peak Temperature (Tp)               | 185°C Maximum              |
| Target Peak Temperature (Tp Target) | 185°C Maximum 2 Times      |
| Time within 5°C of actual peak (tp) | 10 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum         |
| Time 25°C to Peak Temperature (t)   | N/A                        |
| Moisture Sensitivity Level          | Level 1                    |

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

|                                     |                                                       |
|-------------------------------------|-------------------------------------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 5°C/Second Maximum                                    |
| Preheat                             |                                                       |
| - Temperature Minimum (Ts MIN)      | N/A                                                   |
| - Temperature Typical (Ts TYP)      | 150°C                                                 |
| - Temperature Maximum (Ts MAX)      | N/A                                                   |
| - Time (ts MIN)                     | 30 - 60 Seconds                                       |
| Ramp-up Rate (Tl to Tp)             | 5°C/Second Maximum                                    |
| Time Maintained Above:              |                                                       |
| - Temperature (Tl)                  | 150°C                                                 |
| - Time (tL)                         | 200 Seconds Maximum                                   |
| Peak Temperature (Tp)               | 245°C Maximum                                         |
| Target Peak Temperature (Tp Target) | 245°C Maximum 1 Time / 235°C Maximum 2 Times          |
| Time within 5°C of actual peak (tp) | 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times |
| Ramp-down Rate                      | 5°C/Second Maximum                                    |
| Time 25°C to Peak Temperature (t)   | N/A                                                   |
| Moisture Sensitivity Level          | Level 1                                               |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.